

InGaN Venus Blue LED Chip

Type:
ES-CABLV38

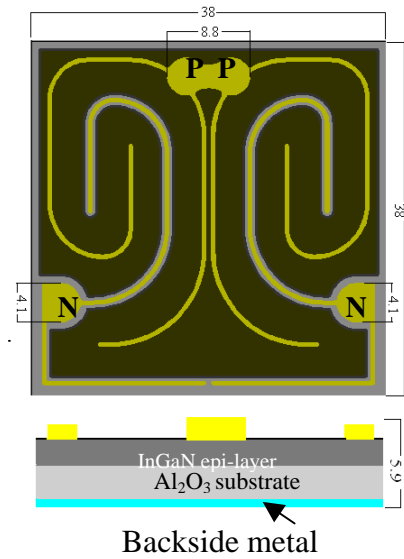
Unit: mil

Features:

- (1) High luminous intensity
- (2) Long operation life
- (3) 100% probing test
- (4) Passivation layer on top
- (5) Backside mirror layer

Characteristics:

- (1) Size
 Chip size : 38 mil x 38 mil ($965 \pm 25 \mu\text{m} \times 965 \pm 25 \mu\text{m}$)
 Chip thickness : 5.9 mil ($150 \pm 10 \mu\text{m}$)
 P bonding pad x 2 : 3.9 mil ($100 \pm 10 \mu\text{m}$)
 N bonding pad x 2 : 4.1 mil ($105 \pm 10 \mu\text{m}$)
- (2) Metallization
 P electrode : Au alloy
 N electrode : Au alloy
 Backside metal : Au alloy
- (3) Structure
 Refer to drawing



Electro-optical characteristics: ⁽¹⁾

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	V_{f1}	$I_f = 10\text{uA}$	1.6	---	---	V
	V_{f2}	$I_f = 350\text{mA}$	---	3.5	3.8	V
Reverse current	I_r	$V_r = 5\text{V}$	---	---	2	uA
Dominant wavelength ⁽²⁾	λ_d	$I_f = 350\text{mA}$	455	460	465	nm
Radiant power ⁽³⁾⁽⁴⁾	P_o	H13	185	---	220	mW
		H14	220	---	255	

- (1) ESD protection during chip handling is recommended.
- (2) Basically, wavelength uniformity is $\lambda_d \pm 5\text{nm}$; however, customers' special requirements are also welcome.
- (3) Customer's special requirements are also welcome.
- (4) Radiant power is determined by a correlation with luminous intensity using a Au-plated TO-18 header without an encapsulant, whereas luminous intensity is measured by **EPISTAR**'s equipment on bare chips.
- (5) Epistar maintains a tolerance of $\pm 15\%$ on the above radiant flux specifications.

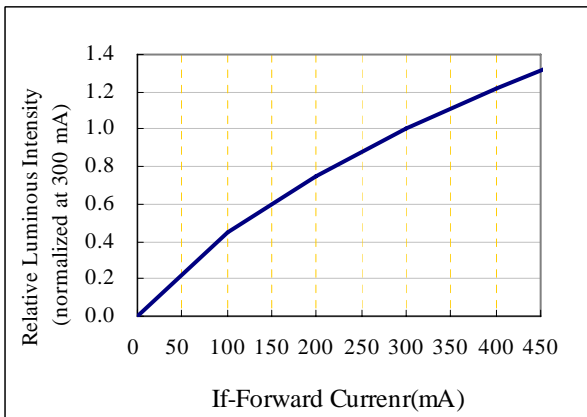


Fig-1 Relative Luminous Intensity vs. Forward current

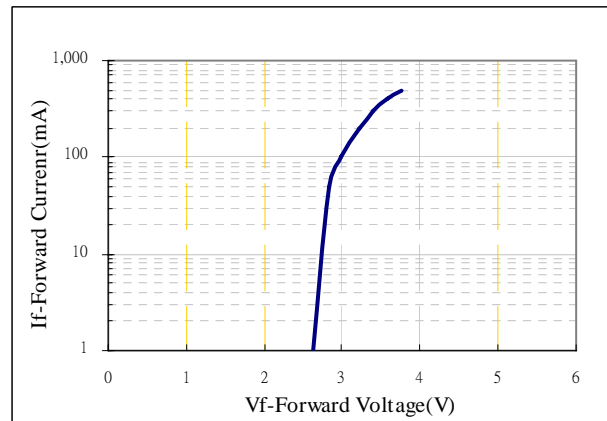


Fig-2 Forward Current vs. Forward Voltage

Absolute maximum ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC current	I_f	$T_a=25^\circ\text{C}$	≤ 450	mA
Reverse voltage	V_r	$T_a=25^\circ\text{C}$	≤ 5	V
Junction temperature	T_j	---	≤ 115	$^\circ\text{C}$
Storage temperature	T_{stg}	chip	-40 ~ +85	$^\circ\text{C}$
		chip-on-tape/storage	0 ~ 40	$^\circ\text{C}$
		chip-on-tape/transportation	-20 ~ +65	$^\circ\text{C}$
Temperature during packaging	---	---	280(<10sec)	$^\circ\text{C}$

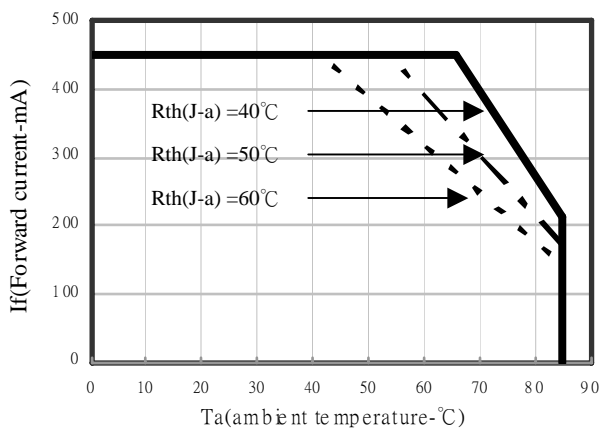


Fig-3 Maximum Driving Forward DC Current vs. Ambient Temperature (Derating based on T_j max. = 115°C)

Applications:

- Backlighting for display and projector
- Signage and channel letters
- Decorating and entertainment lighting
- Architectural and specialty lighting
- Indoor/outdoor application
- Portable light source